

# **Absolute Maximum Ratings** ( $@T_A = +25^{\circ}C$ unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	50	V
Collector-Emitter Voltage	V <sub>CEO</sub>	50	V
Emitter-Base Voltage	$V_{EBO}$	5.0	V
Collector Current	Ic	100	mA
Peak Collector Current	I <sub>CM</sub>	200	mA

#### Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Power Dissipation	(Note 5)	P <sub>D</sub>	400	mW	
Fower Dissipation	(Note 6)		1000	] IIIVV	
Thermal Resistance, Junction to Ambient	(Note 5)	$R_{ heta JA}$	310	°C/W	
	(Note 6)		120	-C/VV	
Thermal Resistance, Junction to Lead	(Note 7)	$R_{ heta JL}$	120	°C/W	
Operating and Storage and Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C	

## ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	200	V	В

#### Electrical Characteristics @TA = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)					·	
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	50	_	V	$I_C = 50\mu A, I_E = 0$	
Collector-Emitter Breakdown Voltage	BV <sub>CEO</sub>	50	_	V	$I_C = 1.0 \text{mA}, I_B = 0$	
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	5.0	_	V	$I_E = 50 \mu A, I_C = 0$	
Collector Cutoff Current	_	_	100	nA	$V_{CB} = 30V$	
Collector Cuton Current	ICBO		5	μΑ	$V_{CB} = 30V, T_A = +150$ °C	
Emitter Cutoff Current	I <sub>EBO</sub>		100	nA	$V_{EB} = 4.0V$	
ON CHARACTERISTICS (Note 9)	ON CHARACTERISTICS (Note 9)					
DC Current Gain	h <sub>FE</sub>	120	270	_	$V_{CE} = 6.0V, I_{C} = 1.0mA$	
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>	_	0.2	V	$I_C = 50 \text{mA}, I_B = 5.0 \text{mA}$	
SMALL SIGNAL CHARACTERISTICS						
Output Capacitance	$C_{ m obo}$		3.5	pF	$V_{CB} = 12V, f = 1.0MHz, I_E = 0$	
Current Gain-Bandwidth Product	f <sub>T</sub>	100	_	MHz	$V_{CE} = 12V, I_{C} = 2.0mA,$ f = 100MHz	

Notes:

- 5. For the device mounted on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady state condition. The entire exposed collector pad is attached to the heatsink.

  6. Same as Note 5, except the exposed collector pad is mounted on 25mm x 25mm 2oz copper.

  7. Thermal resistance from junction to solder-point (on the exposed collector pad).

  8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

- 9. Measured under pulsed conditions. Pulse width  $\leq$  300µs. Duty cycle  $\leq$  2%.



# Typical Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

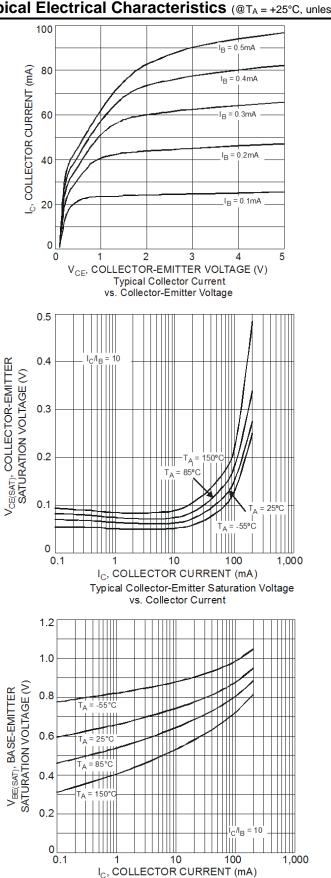
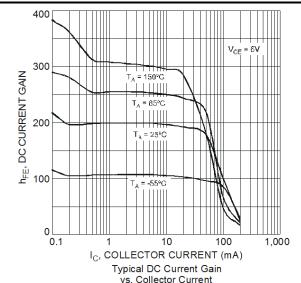
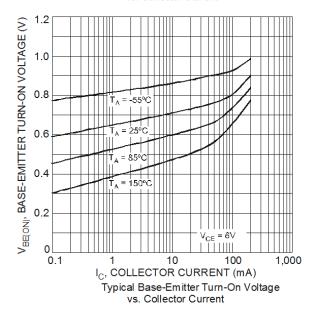


Fig. 6 Typical Base-Emitter Saturation Voltage vs. Collector Current

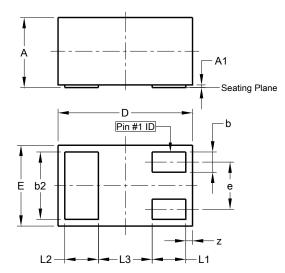






### **Package Outline Dimensions**

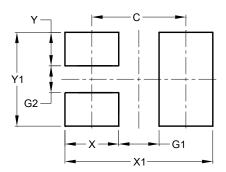
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



X1-DFN1006-3				
Dim	Min	Max	Тур	
Α	0.47	0.53	0.50	
A1	0.00	0.05	0.03	
b	0.10	0.20	0.15	
b2	0.45	0.55	0.50	
D	0.95	1.075	1.00	
Е	0.55	0.675	0.60	
е	ı	-	0.35	
L1	0.20	0.30	0.25	
L2	0.20	0.30	0.25	
L3	-	-	0.40	
Z	0.02	0.08	0.05	
All Dimensions in mm				

## **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.70
G1	0.30
G2	0.20
X	0.40
X1	1.10
Y	0.25
Y1	0.70



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